



### Gamma Radiation Induced Effects in Si p-i-n Photo Diodes

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- Problem statement
   > Objectives
  - Approach
- Progress
  - Physics
  - First calculations
- Summary and Perspectives



STUDIECENTRUM VOOR KERNENERGIE CENTRE D'ÉTUDE DE L'ÉNERGIE NUCLÉAIRE Instrumentation Department: studies of opto-electronics for applications in different nuclear environments



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JET

DEVELOPMENT

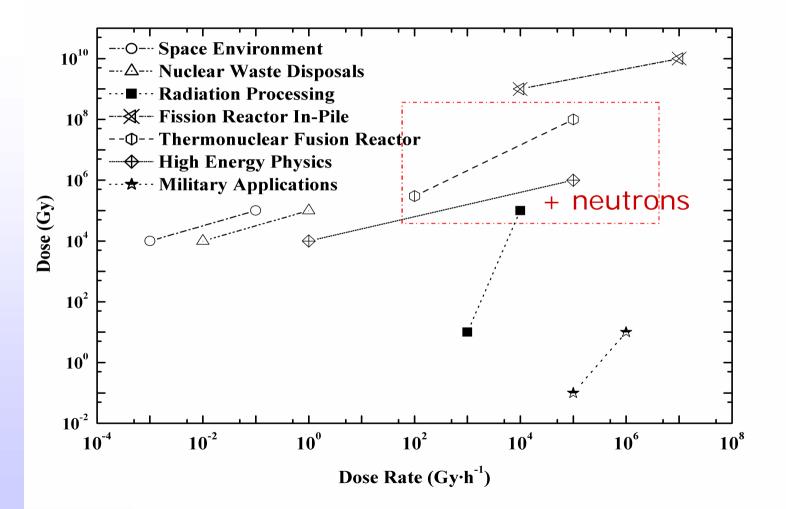




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## We mainly focus on high gamma doses







Laser Diodes and Photo Diodes under radiation



- Mainly studied for space applications
  - particle irradiation (electrons, protons, ions)
  - kGy level gamma doses
- Observe the effects without in depth physical explanation
  - Damage correlation to the displacement (NIEL)
  - NIEL is a macro model for "bulk" structures

✓ Modern O/E devices have complicated layered structures.
 ✓ We are interested in MGy level ionizing doses.



### Our final objectives are to



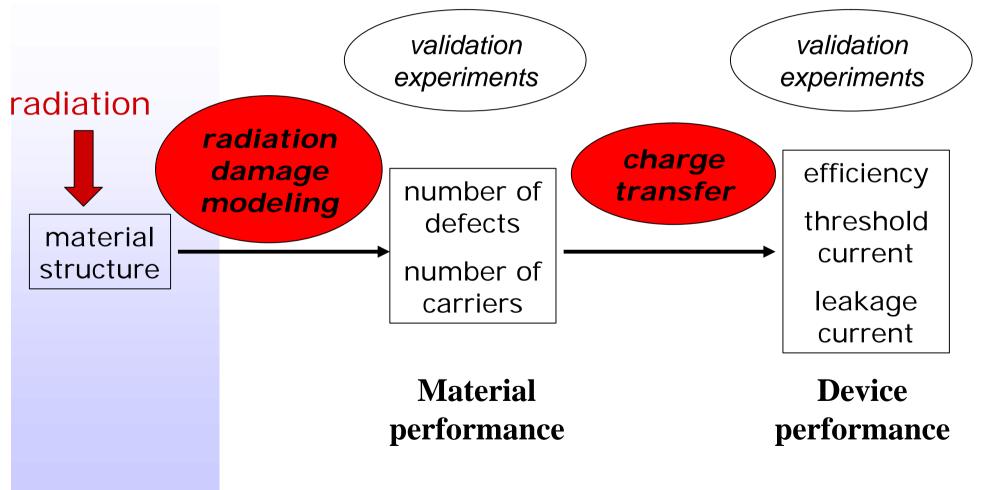
- 1. define predictive radiation damage models for 2 case studies
  - 1. P-i-n photodiodes *Si, InGaAs*...
  - 2. Vertical-cavity surface-emitting lasers (VCSELs) GaAs, AlGaAs...
- 2. find parts of the answer to
  - Is degradation of modern optoelectronic devices due to bulk or interface damage ?
  - 2. How does downscaling of modern optoelectronics affect their radiation response ?
- 3. possibly optimize optoelectronic devices for use in nuclear environments



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## Our approach: from materials to devices







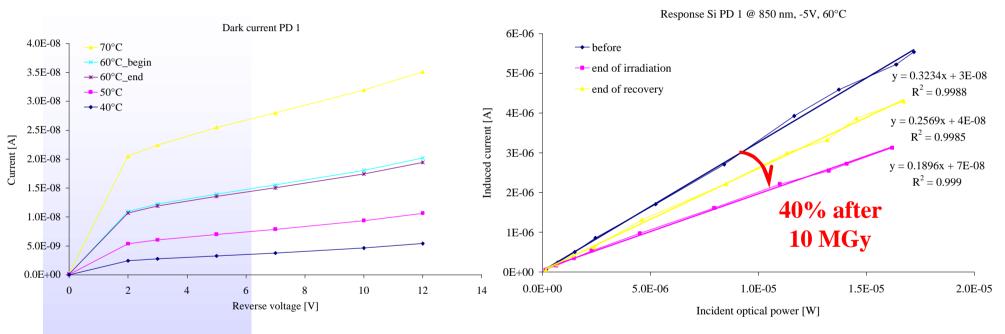
# Si PD can withstand MGy dose levels, but...



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#### dark current increase

#### responsivity decrease



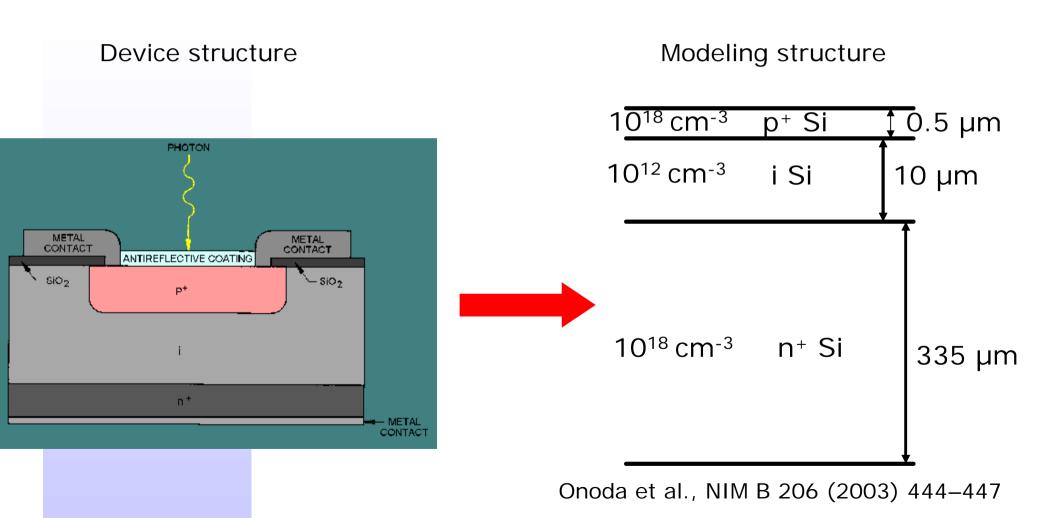
M. Van Uffelen et al., 2004, SPIE Proceedings, vol. 5465

...this behavior is not yet well explained.



# Test structures of a Si p-i-n photo diode







Modeling tools for gamma radiation



#### Penelope

- Electron-photon transport
- ➤ 100 eV 1 GeV

✓ Depth-distribution of deposited charge.
✓ Distribution of energy deposited into the target.

### GEANT4

- CERN, Object-Oriented framework
- Electron, photon and particle transport
- Implemented the Penelope low energy physics

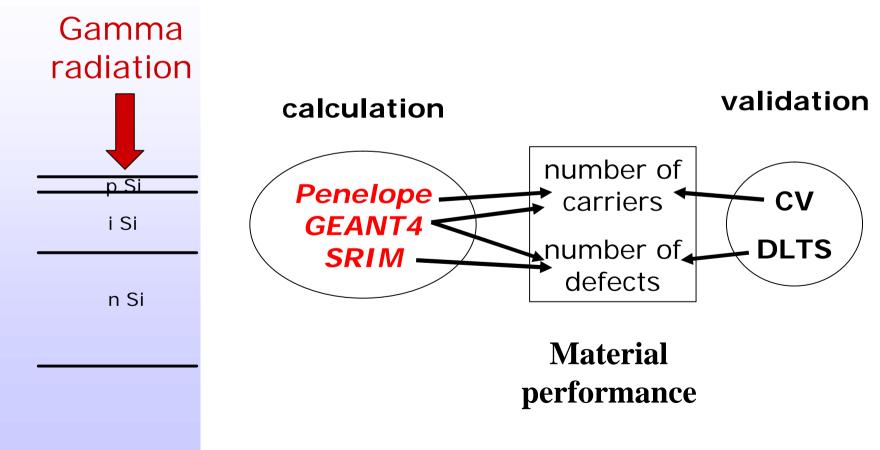
 ✓ Depth-distribution of deposited charge.
 ✓ Distribution of energy deposited into the target.
 ✓ Displacement profile



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Detailed approach for material performance modeling





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Outline



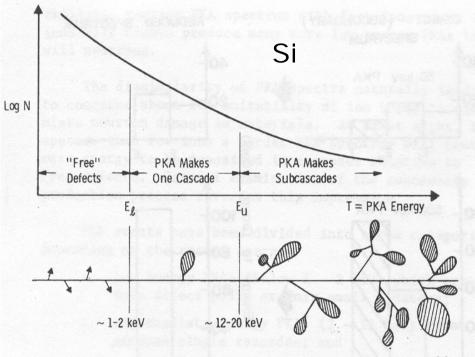
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  - Physics of the processes
  - First calculations
  - CV measurements
- Summary and Perspectives



### Total ionization dose effects are playing significant role in case of Gamma radiation



- Displacement
  - Through Compton electrons
  - Primary Knock-on Atoms with energy lower than 1 keV
  - Only individual defects



S.Wood at al, IEEE Trans. Nucl. Sci., 1981.

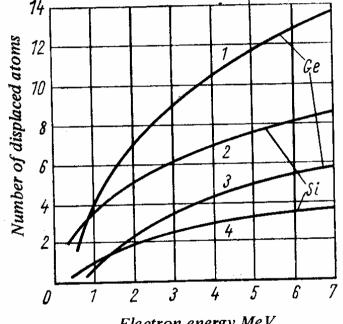


## Displacement of target atoms in Si upon electron and gamma irradiation



K. Gill et al., NIM A, 1996

- vacancy introduction rate- 10<sup>-3</sup>cm<sup>-1</sup>
- divacancy introduction rate- 10<sup>-5</sup>cm<sup>-1</sup>
- type inversion after 110Mrad
- L. Fedina et al., *Phys.stat.sol.(a)*, 1999.
  •clusters of vacancies in Si formed after MeV electron irradiation
  •depends on:
  - ➢point defects
  - ≻thickness of the sample
  - ≻surface type
  - •clusters in Si are more stable compared to GaAs



Electron energy MeV

Figure 3. Number of displaced atoms of germanium and silicon per single incident fast electron  $[E_d 15 / 1, 2/ \text{ and } 30/3, 4/ \text{ eV}]$ 



### Total ionization dose effects are playing significant role in case of Gamma radiation

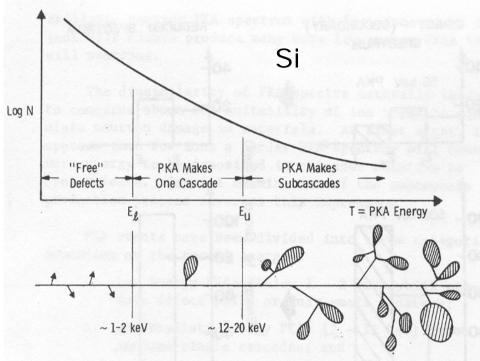


- Displacement
  - Through Compton electrons
  - Primary Knock-on Atoms with energy lower than 1 keV
  - Only individual defects
- Heat

Annealing

### Ionization

Through Compton scattering and photoelectric effect



S.Wood at al, IEEE Trans. Nucl. Sci., 1981.



Outcome from Penelope and its limitations



 Charge depth profilingconsider only electronphoton transport

thickness dependencematerial dependence

Limitations

does not take into account interface imperfections, bulk defects and impurities
 does not include annealing
 does not take dynamics into account (dose rate)

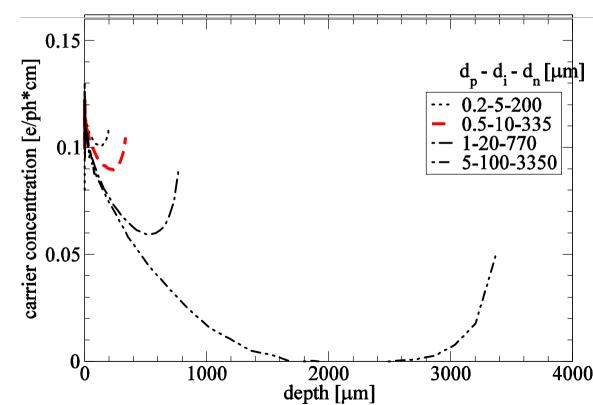
>does not cover displacement
>does not include electric field



# Penelope calculations on Si p-i-n structures



- Two peaks structure
- There is not interface influence in the distribution
- The intensity of back peak decreases
- The code is not suitable for nm structures





Discussion



- insensitive to the doping levels
- missing any interface effects- the mean free path of the electrons is larger than the thickness of the device
- radiation induced carriers will affect lightly doped regions and those closer to the surface



## Limits of the calculations



temperature effects
 impurities and contaminations
 interface stresses
 dose rate effects and accumulation *phenomenology, MD* ....

electron particle transport
 electric field effects
 GEANT4



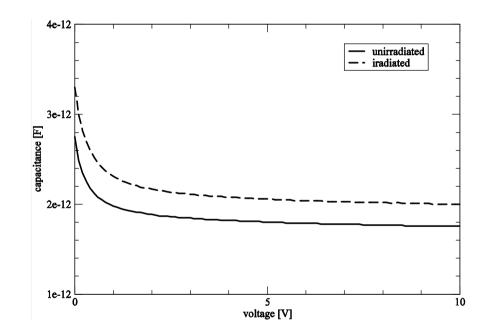
### First CV trials of Si p-i-n PD



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 change in the material properties

- accumulation of charge in the oxide layer?
- intrinsic layer?
- package effects?





Summary



 Penelope calculates almost homogeneous distribution up to 500µm thickness of the structure

"bulk" effects are dominant

- the thinner the device the smaller the amount of radiation induced charges and the smaller the amount of displaced atoms
- lightly doped regions are more affected



Future work



- investigate electric field effects and displacement with Geant4
- additional CV measurements and interpretation
- looking for other suitable techniques to characterize devices